

a loading station disposed in connection with the mainframe having one or more loading station robots;

two or more processing stations disposed in connection with the mainframe, wherein each processing station comprises two or more electrochemical deposition cells;

two or more cleaning modules connected between the loading station and the mainframe; and

two or more post deposition treatment chambers in connection with the loading station.

46. The deposition system of claim 45, further comprising a pass-through cassette disposed above the cleaning modules.

47. The deposition system of claim 45, wherein a processed substrate is transferred from the one of the electrochemical deposition cells into the pass-through cassette and transferred from the pass-through cassette using the loading station robots to one of the post deposition treatment chambers.

REMARKS

This is intended as a full and final response to the Office Action dated June 25, 2002, having a shortened statutory period for response set to expire on September 25, 2002. Please reconsider the claims pending in the application for reasons discussed below.

The Examiner's claim objection to the claim numbering is noted and the renumbering set forth by the Examiner is reflected in this Response.

A replacement declaration is submitted herewith to correct the deficiency identified by the Examiner.

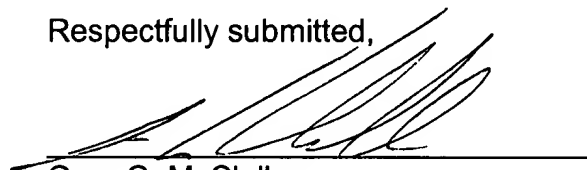
As a result of communications between the Applicants' attorney (whose signature appears below) and the Examiner, it was agreed that the pending claims are patentable over the references of record. Applicants therefore respectfully request allowance of all claims. Further, since no amendments are necessary to facilitate an allowance, the claims are entitled to their full range of equivalents.

Claims 21, 32-36, 38, 41, 44 and 45 stand rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 1, 2, 9 and 10 of U.S. Patent No. 6,136,163. A terminal disclaimer is submitted herewith to overcome the rejection.

The prior art made of record is noted. However, it is believed that the secondary references are no more pertinent to the Applicants' disclosure than the primary references cited in the office action. Therefore, it is believed that a detailed discussion of the secondary references is not deemed necessary for a full and complete response to this office action. Accordingly, allowance of the claims is respectfully requested.

In conclusion, the references cited by the Examiner, neither alone nor in combination, teach, show, or suggest the method or apparatus of the claimed invention. Having addressed all issues set out in the Office Action, Applicants respectfully submit that the claims are in condition for allowance and respectfully request that the claims be allowed.

Respectfully submitted,



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APPENDIX

21. (Amended) An electro-chemical deposition system, comprising:
a mainframe having a mainframe wafer transfer robot[s] disposed therein;
a loading station disposed in connection with the mainframe having one or more loading station robots;
one or more processing stations disposed in connection with the mainframe, wherein each processing station comprises one or more electrochemical deposition cells; and
one or more post deposition treatment chambers disposed in connection with the mainframe.
22. (Amended) The deposition system of claim 21, wherein the loading station further comprises one or more cassette receiving areas and at least one wafer orienter[d] to set a wafer.
23. (Amended) The deposition system of claim 21, wherein the one or more post deposition treatment chambers are one or more spin-rinse-dry modules and wherein the one or more loading station robots transfer wafers between the one or more cassette receiving areas and the one or more spin-rinse-dry modules.
25. (Amended) The deposition system of claim 21, wherein [the] one or more spin-rinse-dry modules are connected between the loading station and the mainframe.
29. (Amended) The deposition system of claim 21, wherein the mainframe wafer transfer robot comprises a plurality of individual robot arms to provide independent access of wafers in the one or more processing stations and [the] one or more spin rinse dry modules.
35. (Amended) The deposition system of claim 34, further comprising one or more spin-rinse-dry modules and wherein at least one of the one or more chemical storage tanks provides one or more chemicals to the spin-rinse-dry modules.

37. (Amended) The deposition system of claim [21]36, further comprising a pass-through cassette disposed above the spin-rinse-dry modules.